Product / Package Information

Package	QFN
Body Size (mm)	7 X 7
Lead Count	48
Terminal Finish	NiPdAu
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	5.80E-02	93.70	937000	41.68	416757
Thermosets	Epoxy Resin	Proprietary	1.86E-03	3.00	30000	1.33	13343
Thermosets	Phenol Resin	Proprietary	1.86E-03	3.00	30000	1.33	13343
Other inorganic materials	Carbon Black	1333-86-4	1.86E-04	0.30	3000	0.13	1334
Subtotal			6.19E-02	100.00	1000000	44.48	444778

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	6.65 E-02	97.50	975000	47.75	477511
Copper & its alloys	Iron	7439-89-6	1.60 E-03	2.35	23500	1.15	11509
Copper & its alloys	Zinc	7440-66-6	8.18 E-05	0.12	1200	0.06	588
Copper & its alloys	Phosphorus	7723-14-0	2.05 E-05	0.03	300	0.01	147
Subtotal			6.82 E-02	100.00	1000000	48.98	489755

Internal / External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Nickel & its alloys	Nickel	7440-02-0	1.35 E-03	97.30	973000	0.97	9725
Precious metals	Palladium	7440-05-3	3.06 E-05	2.20	22000	0.02	220
Precious metals	Gold	7440-57-5	6.96 E-06	0.50	5000	0.00	50
Subtotal			1.39 E-03	100.00	1000000	1.00	9995

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	9.74 E-04	100.0	1000000	0.70	6997

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	5.98 E-03	100.0	1000000	4.30	42979

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	6.16 E-04	80.50	805000	0.44	4425
Other organic materials	Carbocyclic Acrylates	Proprietary	7.65 E-05	10.00	100000	0.05	550
Other organic materials	Bismaleimide resin	Proprietary	2.30 E-05	3.00	30000	0.02	165
Other organic materials	2-preponoic acid, 2-methyl	68586-19-6	2.30 E-05	3.00	30000	0.02	165
Others	Additive	Proprietary	2.30 E-05	3.00	30000	0.016	165
Other organic materials	Dicumyl peroxide	80-43-3	3.83 E-06	0.50	5000	0.003	27
Subtotal			7.65 E-04	100.00	1000000	0.55	5497

	Weight (g)	Percentage (%)	PPM
Package Totals	**1.39 E-01**	**100.00**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES